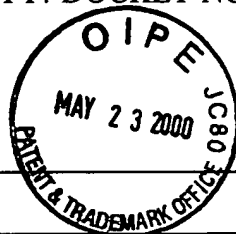


Form PTO-1449 (modified)

List of Patents and Publications
For Applicant's Information
Disclosure Statement
(Use several sheets if necessary)

ATTY. DOCKET NO: 5298-05500

SERIAL NO: 09/476,669



APPLICANT: Lau

FILING DATE: December 30, 1999

GROUP: 2811

U.S. PATENT DOCUMENTS

EXAM. INITIALS	REF. DES	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
JC	AA	4,970,176	11/13/90	Tracy et al.			
JC	AB	5,108,570	4/28/92	Wang			
JC	AC	5,108,951	4/28/92	Chen et al.			
JC	AD	5,270,255	12/14/93	Wong			
JC	AE	5,288,665	2/22/94	Nulman			
JC	AF	5,358,616	10/25/94	Ward			
JC	AG	5,371,042	12/6/94	Ong			
JC	AH	5,378,660	1/3/95	Ngan et al.			
JC	AI	5,443,995	8/22/95	Nulman			
JC	AJ	5,600,182	2/4/97	Schinella et al.			
JC	AK	5,665,659	9/9/97	Lee et al.			
JC	AL	5,693,564	12/2/97	Yu			
JC	AM	5,731,245	3/24/98	Joshi et al.			

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

JC	AN	Xu et al., "Plar Multilevel Metallization Technologies for ULSI Devices," SPIE Vol. 2335, 1994, pp. 70-79.
JC	AO	Xu et al., "A1 planarization processes for multilayer metallization of quarter micron devices," Thin Solid Films, Vol. 253, 1994, pp. 367-371.
JC	AP	Singer, "The Interconnect Challenge: Filling Small, High Aspect Ratio Contact Holes," Semiconductor International, August 1994, 5 pages.
JC	AQ	Robinson, "A1 hits sub-0.25 micron vias," pp. 37 and 42, Electronic Engineering Times, Issue 939, February 1997.
JC	AR	Metal Deposition Products, Applied Materials-Products and Services, 5 pages, printed November 1999, © 1999 Applied Materials, Inc.
JC	AS	"Ionized Physical Vapor Deposition," printed December 1999, www.ece.neu.edu/edsnu/hopwood, 8 pages.

EXAMINER:

J. Cantelero

DATE CONSIDERED:

2/28/01

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the patent owner.